Tummala / Kosec / Jones

Electronic Packaging for High Reliability, Low Cost Electronics

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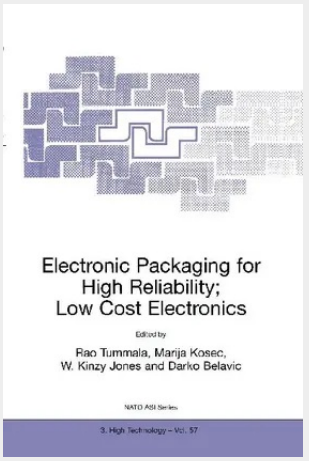

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